

Product Name:	HPL - 578 Bergstik		
	Bergstik		
Product Manager:	SORNAY Médéric		
Subject:	Notification of Planned Change		
Distribution:	Affected customers		
Type of Change:	Materials Change		
Change Description:	Introduction of plastic resin grade PA9T material across the pool of resin used for Bergstik series connectors produced in Amphenol Nantong, China to meet moisture sensitivity level- MSL1 specification.		
Reason for Change:	Presently using plastic resin grade PA46, which is non Halogen Free and MSL3 level. The new resin grade material PA9T introduced for Amphenol FCI Nantong, China production : PA9T is non Halogen Free with MSL1 specification as part of material supply improvements.		
Affected Parts:	See Affected Parts.xls		
Effective Date of Change:	November,01 2027		
Last Time Buy Date:	NA		
Earliest Disty Return Date:	NA		
Last Time Shipment Date	NA		
Datasheet Attached?	Yes		
Qual/Test Data Attached?	Yes		
Samples Availability Date:	01 October ,2026		
Available Alternatives?			
Questions?	<i>Contact your local ACS Representative, or Product Manager</i>		
	<i>SORNAY Médéric / Product Manager</i>		
	<i>mederic.sornay@amphenol-fci.com</i>		

Note:

Customers should contact Product Line Manager (or their local Amphenol Representative) directly regarding any concern on the PCN. Lack of any such customer feedback within three weeks of PCN release date will be interpreted as non-objection .

富加宜电子（南通）有限公司

连接器技术中心实验室

FCI Nantong Ltd. Connector Technology Center Laboratory

检测报告

Test Report

检测目的: Product Qualification
Purpose
委托方: Nantong plant
Applicant
联系方式: Mike.Zhou@amphenol-fci.com
Contact info.

产品名称: Bergstik 产品规格: 10188066-420VLF
Product name connector Product PN

收样日期: 2026-7-3 测试时间: 2026-7-6~2026-7-18
Samples received date Testing period

依据标准: BUS-12-050 L
Specification

结论: PASS
Conclusion

编制 Sarah Zhang
Edit

批准 Cao
Approval

审核 Cao
Check



报告发布: 2026 年 7 月 20 日
Release date Year Month Day

声 明 Statement

1, 本报告仅对所检样品负责, 不代表批次产品表现。

This report is only responsible for the samples tested and does not represent the batch behavior.

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5, 如对报告有异议, 请于报告收到之日起【15】个工作日内以书面形式向本实验室提出。

Any objection to this report, please submit to laboratory in writing within 15 working days from the date of receipt.

1, TESTING PURPOSE

This report summarizes the results conduct on Bergstik Connector to evaluate if the products can meet the FCI product specification BUS-12-050 L and requestor's requirement.

2, SAMPLE INFORMATION

Received samples status		All in good condition and suitable for testing		
Information from requester				
Sample name	PN	Terminal base material	Contact plating	Housing material
Bergstik header	10188066-420VLF	Copper alloy	100u" Min Tin	PA 9T
Photo				

3, TEST MATRIX AND CONCLUSION

Items	Test group and sequence		
	1A	1B	2
Visual Examination	1	1,10	1,3
Insulation Resistance		2,5,8	
Dielectric Withstanding Voltage		3,6,9	
Contact Retention Force	2		
Thermal Shock		4	
High Temperature Life		7	
Resistance to Soldering Heat			2
Sample Quantity (PCS)	1	5	3
Conclusion	PASS	PASS	PASS

4, TESTING METHOD AND REQUIREMENT

No.	Item	Method	Condition	Requirement
1	Visual Examination	EIA-364-18 B	10X magnification	Free from blistering, discoloration, cracks, etc.

2	Insulation Resistance	EIA-364-21 F	500VDC, 60S (3 adjacent terminals and 3 opposing terminals)	Insulation resistance no less than 5000MΩ
3	Dielectric Withstanding Voltage	EIA-364-20 F	1500VAC, 50s, 1mA (3 adjacent terminals and 3 opposing terminals)	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)
4	Contact Retention Force	EIA-364-29 D Method C	25.4 mm/minute 3 readings per connector	≥8.9N (2 lbs, post inserted contact)
5	Thermal Shock	EIA-364-32 G	-65~105°C, 1h per cycle, 5 cycles	No evidence of cracking or other physical damage
6	High Temperature Life	EIA-364-17 C	105°C, 250h	No damage
7	Resistance to Soldering Heat	EIA-364-56 E	Procedure 3, Condition H, Solder temperature: 275°C, Immersion time: 10s, 2 passes	No evidence of physical or mechanical damage

5, TESTING RESULT

5.1 GROUP 1A

5.1.1 Result summary

Step #	Test	Requirement	Result	Comment
1	Visual Examination	Free from blistering, discoloration, cracks, etc.	Free from blistering, discoloration, cracks, etc.	All Products PASS
2	Contact retention force	≥8.9N	≥67.4 N	All Products PASS

5.1.2 Force result details

Unit: N	Terminal 1	Terminal 2	Terminal 3
Contact retention force	71.0	68.5	67.4

5.2 GROUP 1B

5.2.1 Result summary

Step #	Test	Requirement	Result	Comment
1	Visual Examination	Free from blistering, discoloration, cracks, etc.	Free from blistering, discoloration, cracks, etc.	PASS
2	Insulation Resistance	Insulation resistance no less than 5000MΩ	Insulation resistance no less than 5000MΩ	PASS
3	Dielectric Withstanding Voltage	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	PASS
4	Thermal Shock	No evidence of cracking or other physical damage	No evidence of cracking or other physical damage	PASS

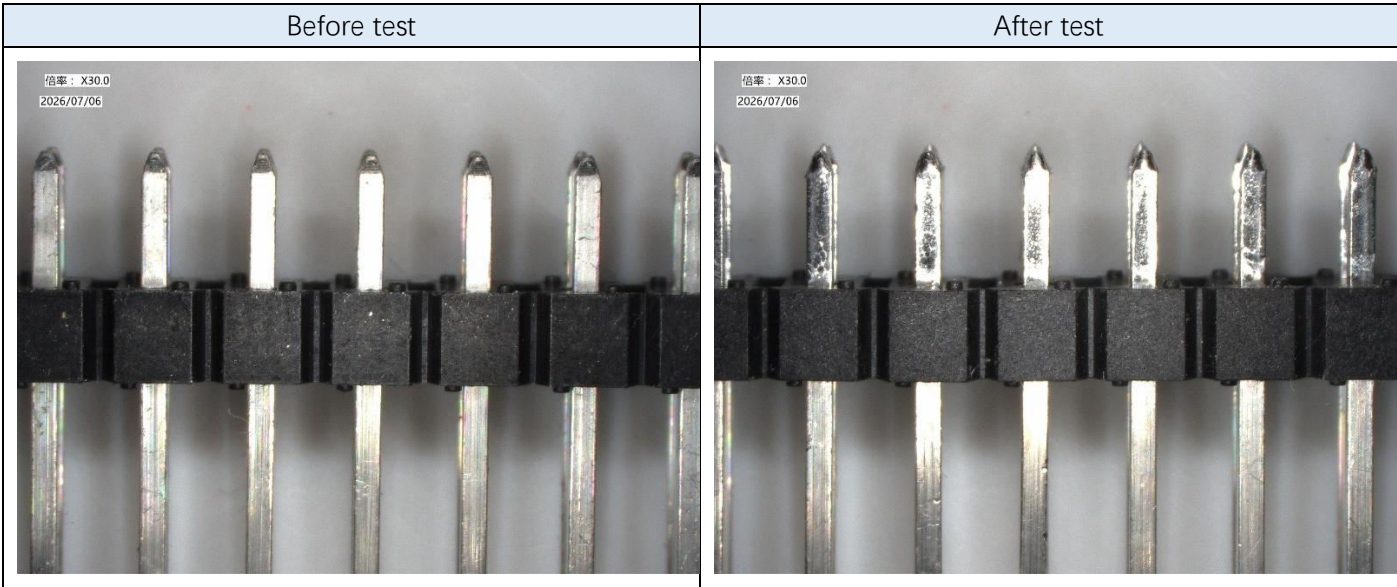
5	Insulation Resistance	Insulation resistance no less than 5000MΩ	Insulation resistance no less than 5000MΩ	PASS
6	Dielectric Withstanding Voltage	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	PASS
7	High Temperature Life	No damage	No damage	PASS
8	Insulation Resistance	Insulation resistance no less than 5000MΩ	Insulation resistance no less than 5000MΩ	PASS
9	Dielectric Withstanding Voltage	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	No evidence of arc-over, insulation breakdown, or excessive leakage current (>1 mA)	PASS
10	Visual Examination	Free from blistering, discoloration, cracks, etc.	Free from blistering, discoloration, cracks, etc.	PASS

5.3 GROUP 2

5.3.1 Result summary

Step #	Test	Requirement	Result	Comment
1	Visual Examination	Free from blistering, discoloration, cracks, etc.	Free from blistering, discoloration, cracks, etc.	PASS
2	Resistance to Soldering Heat	No evidence of physical or mechanical damage	No evidence of physical or mechanical damage	PASS
3	Visual Examination	Free from blistering, discoloration, cracks, etc.	Free from blistering, discoloration, cracks, etc.	PASS

5.3.2 Resistance to soldering heat details



6, EQUIPMENT USED INFORMATION

Item	ID Number	Last Cal. date	Cal. Due date
Microscope	NT#2981	/	/
Automatic Insertion and Extraction Force Machine	B#2196	2025-10-10	2026-10-09
Thermal shock chamber	B#2453	2025-8-30	2026-8-29
Hot Chamber	B#1900	2026-4-2	2027-4-1
Hipot Tester	B#1996	2025-10-10	2026-10-09
Solder Pot	B#2566	2026-4-2	2027-4-1

7, REVISION RECORD

Revision Level	Affected Pages	Description	Release Date
1	/	Original Release	2026-7-20

**Note: The latest version will replace the previous version by default.*

——End of Report——

Hi TTI Team,

Please consider releasing our latest Global Product Process Change Notification ' (PCN) to affected customers

PCN Reference	Item Number	Change	Effective Date of Change	HPL Code Name	Sold
PCN26169	67997-410HLF	MATERIALS CHANGE	NOVEMBER 1, 2027	578 - BERGSTIK	TTI E LTD
PCN26169	68021-404HLF	MATERIALS CHANGE	NOVEMBER 1, 2027	578 - BERGSTIK	TTI E LTD
PCN26169	68691-412HLF	MATERIALS CHANGE	NOVEMBER 1, 2027	578 - BERGSTIK	TTI E LTD